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HUAWEI FusionServer E9000 is a new-generation blade server that integrates computing, storage, switching, and management subsystems to form a powerful converged infrastructure platform. The E9000 is an industry-leading hardware computing platform that improves competitiveness based on its availability, computing density, energy consumption, low emissions, midplane bandwidth, intelligent management and services, elastic configuration, flexible computing and storage expansion capabilities, low network latency, and acceleration functions.

Chassis	 E9000 chassis						
Compute node	 CH121 V3 compute node	 CH140 V3 compute node	 CH220 V3 I/O expansion compute node	 CH222 V3 Storage expansion compute node	 CH225 V3 All-flash compute node	 CH226 V3 Storage expansion compute node	 CH242 V3 compute node
Switch module	 CX110 GE switch module	 CX111 GE switch module	 CX116 GE pass through module	 CX210 8G FC Switch module	 CX220 16G FC switch module	 CX310 10GE/FCoE converged switch module	 CX311 10GE/FCoE/FC converged switch module
	 CX317/318 10GE pass through module	 CX320 10GE/40GE/FCoE/FC converged switch module	 CX611 IB QDR/FDR switch module	 CX620 IB EDR switch module	 CX912 10GE/FC multi-plane switch module	 CX710 40GE Switch Module	 CX915 GE/8G FC multi-plane switch module

Underpinned by leading technology and architecture, the E9000 applies Huawei's extensive technical experience in the ICT field coupled with Huawei's proprietary technologies and solutions to ensure industry-leading quality and distinctive functionality.

Highest computing density in a chassis

- Supports Intel® Xeon® E5 v3, E5 v4, E7 v3 and E7 v4 series processors.
- Supports two small 2-socket compute nodes in a half-width slot.

Best scalability

- Supports free combinations of 2-socket and 4-socket compute nodes.
- Supports standard PCIe card expansion on half-width compute nodes.
- Supports 6 standard PCIe card expansion or 2 full-height full-length dual slots GPGPU cards on full-width compute nodes
- Supports 2 standard PCIe card expansion on a 4-socket compute node.

Best internal storage capability

- Supports 8 x 2.5" hard disks on a full-width, 4-socket compute node.
- Support all-flash compute nodes and 12 NVMe SSDs embedded in full-width nodes, delivering superior data throughput.
- Supports 15 x 2.5" hard disks or 6 x 3.5" hard disks on a full-width storage expansion compute node.

Highest switching and I/O capability

- Supports a midplane capable of 32Tbit/s.
- Provides 128 x 10GE ports on a chassis.
- Supports GE/10GE/40GE/FCoE/FC/IB EDR switching and evolution to 100GE.

Typical applications

The E9000 integrates computing, storage, and networking resources to meet carriers' and enterprises' requirements for high-end core applications such as private clouds and high-performance computing.

HUAWEI FusionServer E9000 Chassis

(E9000 chassis)

Superb performance

- Supports evolution based on three generations of high-performance Intel processors.
- Supports 15 x 2.5" disks or 6 x 3.5" disks or 12 x NVMe SSDs in a full-width slot.
- Supports I/O acceleration using GPUs, PCIe SSDs, and DSP.
- Supports half-width/700 W and full-width/1400 W for heat dissipation and power supply.
- Supports 40GE and IB EDR (100G) and evolution to 100GE.

Converged architecture

- Adopts a modular design for computing, storage, switching, power supply, and cooling.
- Supports a dynamically scalable architecture by providing 2-socket and 4-socket compute nodes.
- Provides various switch modules (such as GE, 10GE, 40GE, FC, FCoE, and InfiniBand) that can be flexibly configured based on service requirements.

Green and Reliable

- Support liquid cooling system, power saving >40%, PUE ≤1.1
- Adopts efficient Platinum and Titanium AC PSMs with more than 96% power conversion efficiency.
- Implements dynamic energy saving management functions.
- Optimizes system air ducts to optimize heat dissipation.
- Supports fully redundant function modules to enable seamless switchover.
- Uses a passive midplane to prevent single point of failures.



The E9000 chassis is 12 U high and features an optimized layout structure to maximally use space. It provides 16 slots and redundant power supply modules (PSMs), heat dissipation modules, management modules, and switch modules. The E9000 chassis can be installed in a standard 19-inch rack at a depth of at least 1,000 mm. Two types of E9000 chassis are provided: AC and DC.

Technical Specifications

Form factor	12 U
Blade	16 half-width slots or 8 full-width slots; supports flexible configurations of single-slot, dual-slot, full-width, and half-width nodes and can accommodate up to 16 Huawei CH series half-width compute nodes
Switch module	4 slots for Huawei CX series switch modules provide a midplane switching capability of 32Tbit/s. CX110 GE switch module: 12 x GE + 4 x 10GE uplink, 32 x GE downlink CX111 GE switch module: 12 x GE+4 x 10GE uplink, 32 x GE downlink CX116 GE pass through module: 32 x GE uplink, 32 x GE downlink CX210 8G FC switch module: 8 x 8G FC uplink, 16 x 8G FC downlink CX220 16G FC switch module: 8 x 16G FC uplink, 16 x 16G FC downlink CX310 10GE switch module: 16 x 10GE uplink, 32 x 10GE downlink CX311 10GE/FCoE converged switch module: 16 x 10GE + 8 x 8G FC uplink, 32 x 10GE downlink CX317 10GE pass through module: 32 x 10GE uplink, 32 x 10GE downlink CX318 10GE pass through module: 32 x 10GE uplink, 32 x 10GE downlink CX320 10GE/40GE/FCoE converged switch module: 8x10GE+2x40GE uplink (with 8x10GE/8G FC flexible interface card optional), 32x10GE downlink CX611 InfiniBand switch module (QDR 40Gbit/s, FDR 56Gbit/s): 18 x QDR/FDR uplink, 16 x QDR/FDR downlink CX620 IB EDR switch module: 18 x EDR uplink, 16 x EDR downlink CX710 40GE switch module: 8 x 40GE uplink, 16 x 40GE downlink CX912 multi-plane switch module; supports FC ports: 16 x 10GE + 8 x 8G FC uplink, 32 x 10GE/16 x 8G FC downlink CX915 multi-plane switch module: 4x10GE+12xGE+8x8G FC uplink, 32xGE+16x8G FC downlink
PSM	AC/DC PSM: Maximum six 3000W/2000W AC or six 2500W DC hot-swappable PSUs, N+N or N+M redundant
Fan module	Provides 14 hot-swappable fan modules in N+1 redundancy mode
Management	Complies with IPMI v2.0 and supports management functions such as remote startup, shutdown, reset, logging, hardware monitoring, SOL, KVM over IP, virtual media, fan module monitoring, and PSM monitoring Supports 1+1 redundancy Provides a local KVM port for server management
Power supply	110 V/220 V AC or -48 V DC or HVDC
Operating temperature	5°C to 40°C
Dimensions	442mm(width) x 840mm(depth) x 530mm(height)

HUAWEI CH121 V3 Compute Node

High density and large memory

- Supports the full series of Intel® Xeon® E5-2600 v3/v4 processors to deliver up to 2*22 cores of computing capacity.
- Provides 24 DDR4 DIMMs. Provides a maximum capacity of 1.5TB
- Supports 2 x 2.5" SAS/SATA HDDs or SSDs. supports 2 x 2.5" NVMe SSDs.



Minimum energy for maximum efficiency

- Adopts the dynamic energy saving and power capping technologies to optimally manage and control power consumption with power remarkably reduced in low-load operating.
- Applies superb design, manufacturing processes, and components to ensure high quality.

Intelligent platform for strong management

- Reduces O&M costs by supporting remote deployment and fault location technologies such as SOL, KVM over IP, virtual DVD-ROM drive, WebUI and IPMI 2.0-compliant.
- Provides efficient and secure power consumption analysis and control capabilities.
 - Complies with Intel® NM 3.0.
 - Provides a sub-3s power capping response on each compute node to optimize power consumption control.
 - Supports an intelligent and secure power-off mode for compute nodes.
- Supports the black box function to facilitate quick fault location and service recovery.
- Fault Diagnostic Management 2.0 (FDM 2.0) accurately locates 93% hardware faults, greatly improving O&M efficiency.

The CH121 V3 combines dense computing capabilities with an ultra-large memory capacity. Optimized for enterprise service applications such as virtualization, cloud computing, and high-performance computing, the CH121 V3 employs Intel® Xeon® E5-2600 v3/v4 series processors (up to 145 W) and supports up to 24 DDR4 DIMM slots, 2 internal hard disks, and 1 standard PCI x16 full-height half-length card.

Technical Specifications

Form factor	Half-width 2-socket compute node
Number of processors	1 or 2
Processor model	Intel® Xeon® E5-2600 v3/v4 series
Number of DIMMs	24 DDR4 DIMMs, providing a maximum memory capacity of 1.5 TB
Internal Storage	2 x 2.5" SSDs, SAS HDDs, or SATA HDDs, supporting 2 x NVMe SSDs Built-in flash memory: 2 x SATA DOM 2 x Micro SD cards (Raid1) 1 x USB 3.0 Disk
RAID support	RAID 0 and 1
PCIe expansion	2 PCIe x16 mezz modules 1 standard PCIe x16 full-height half-length card
Operating systems supported	Microsoft Windows Server 2008/2012 Red Hat Enterprise Linux SUSE Linux Enterprise Server Oracle Linux CentOS Huawei Fusionsphere Citrix XenServer VMware
Operating temperature	5°C to 40°C
Dimensions	Height: 60.46 mm Width: 210 mm Depth: 537.2 mm

HUAWEI CH140 V3 Compute Node

Outstanding computing performance based on ultra high density

- Supports the full series of Intel® Xeon® E5-2600 v3/v4 processors to deliver up to 2*22 cores of computing capacity; a half-width slot supports two small slots in two layers for installing two independent 2-socket compute nodes.
- provides eight DIMM slots on a 2-socket compute node, supporting a DDR4 memory capacity of up to 512 GB on a 2-socket compute node.
- Supports 2 Micro SD cards on a 2-socket compute node, supporting raid 1.
- Supports one internal 2.5" SATA HDD or SSD on a 2-socket compute node.



High efficiency and energy-saving

- Uses the dynamic energy saving and power capping technologies to optimally manage and control power consumption with power reduced in low-load operating.
- Adopts the carrier-class design, manufacturing process, and component selection to ensure high quality.

Easy management with the intelligent platform

- Reduces O&M costs by using remote deployment and fault locating methods including SOL, KVM over IP, virtual CD-ROM drive, and WebUIs in compliance with IPMI 2.0.
- Supports efficient and secure power consumption analysis and control capabilities.
 - Complies with Intel® NM 3.0.
 - Implements efficient power consumption control by supporting power capping operations within 3s on a compute node.
 - Supports an intelligent and secure power-on mode for compute nodes.
- Supports the black box function to facilitate fault location, quickly recovering services.
- Fault Diagnostic Management 2.0 (FDM 2.0) accurately locates 93% hardware faults, greatly improving O&M efficiency.

Optimized for HPC and computing-dense enterprise services, the CH140 V3 provides ultra high computing capabilities. A half-width slot supports two 2-socket compute nodes. Each compute node can be maintained independently. The CH140 V3 uses Intel® Xeon® E5-2600 v3/v4 series processors and supports eight DIMM slots and one hard disk, as well as built-in 2 x Micro SD slots supporting RAID 1.

Technical Specifications

Form factor	Two 2-socket twin compute nodes in a half-width slot
Number of processors	1 or 2 in each 2-socket compute node
Processor model	Intel® Xeon® E5-2600 v3/v4 series
Number of DIMMs	8 DDR4 DIMMs for each 2-socket compute node
Internal Storage	One 2.5" SSD/SATA for each 2-socket compute node 2 x Micro SD cards (Raid1)
PCIe expansion	2 twin nodes share 2 MEZZ modules
Operating systems supported	Microsoft Windows Server 2008/2012 Red Hat Enterprise Linux SUSE Linux Enterprise Server Oracle Linux Oracle Solaris CentOS Huawei Fusionsphere Citrix XenServer VMware
Operating temperature	5°C to 35°C
Dimensions	210mm(width) x 537.2mm(depth) x 60.46mm(height)

HUAWEI CH220 V3 I/O Expansion Compute Node

Outstanding expandability

- Supports the full series of Intel® Xeon® E5-2600 v3/v4 processors to deliver up to 2*22 cores of computing capacity.
- Provides 6 standard PCIe x16 full-height slots for supporting various PCIe configuration modes, including 6 full-height half-length single-slots, 1 full-height full-length dual-slot and four full-height half-length single slots, or 2 full-height full-length dual-slots. The cables to the 2 standard PCIe cards are routed from the front panel.
- Provides 16 DDR4 DIMMs with the maximum total memory capacity of 1 TB.



Minimum energy for maximum efficiency

- Adopts the dynamic energy saving and power capping technologies to optimally manage and control power consumption with power remarkably reduced in low-load operating.
- Applies superb design, manufacturing processes, and components to ensure high quality.

Intelligent platform for strong management

- Reduces O&M costs by supporting remote deployment and fault location technologies such as SOL, KVM over IP, virtual DVD-ROM drive, WebUI and IPMI 2.0-compliant.
- Provides efficient and secure power consumption analysis and control capabilities.
 - Complies with Intel® NM 3.0.
 - Provides a sub-3s power capping response on each compute node to optimize power consumption control.
 - Supports an intelligent and secure power-off mode for compute nodes.
- Supports the black box function to facilitate quick fault location and service recovery.
- Fault Diagnostic Management 2.0 (FDM 2.0) accurately locates 93% hardware faults, greatly improving O&M efficiency.

Designed for application acceleration scenarios, VDI, virtualization and databases, the CH220 V3 provides superior scalability. Featuring Intel® Xeon® E5-2600 v3/v4 series processors and support for up to 16 DIMM slots, 2 internal hard disks, and 6 standard PCI cards for various PCIe configurations, the CH220 V3 can be expanded for I/O acceleration components such as PCIe SSDs, GPUs, and HPC acceleration components.

Technical Specifications

Form factor	Full-width 2-socket compute node
Number of processors	1 or 2
Processor model	Intel® Xeon® E5-2600 v3/v4 series
Number of DIMMs	16 DDR4 DIMMs, providing a maximum memory capacity of 1 TB
Internal Storage	2 x 2.5" SSDs, SAS/SATA HDDs Built-in Flash memory: 2 x SATA DOM 2 x Micro SD cards (Raid1) 1 x USB 3.0 Disk
RAID support	RAID 0 and 1
PCIe expansion	2 PCIe x16 + 2 PCIe x8 mezz modules, supporting six standard PCIe cards. The following configuration modes are supported: a. 6 full-height half-length single-slots b. 1 full-height full-length dual-slot and four full-height half-length single-slots c. 2 full-height full-length dual-slots
Operating systems supported	Microsoft Windows Server 2008/2012 Red Hat Enterprise Linux SUSE Linux Enterprise Server Oracle Linux CentOS Huawei Fusionsphere Citrix XenServer VMware
Operating temperature	5°C to 40°C
Dimensions	Height: 60.46 mm Width: 423 mm Depth: 537.2 mm

HUAWEI CH222 V3 Storage Expansion Compute Node

Super storage and computing capabilities

- Supports the full series of Intel® Xeon® E5-2600 v3/v4 processors to deliver up to 2*22 cores of computing capacity.
- Provides 24 DDR4 DIMMs. Provides a maximum capacity of 1.5TB
- Supports 15 x 2.5" SAS/SATA HDDs or SSDs, which provide the highest storage capacity on a single node.



Minimum energy for maximum efficiency

- Adopts the dynamic energy saving and power capping technologies to optimally manage and control power consumption with power remarkably reduced in low-load operating.
- Applies superb design, manufacturing processes, and components to ensure high quality.

Intelligent platform for strong management

- Reduces O&M costs by supporting remote deployment and fault location technologies such as SOL, KVM over IP, virtual DVD-ROM drive, WebUI and IPMI 2.0-compliant.
- Provides efficient and secure power consumption analysis and control capabilities.
 - Complies with Intel® NM 3.0.
 - Provides a sub-3s power capping response on each compute node to optimize power consumption control.
 - Supports an intelligent and secure power-off mode for compute nodes.
- Supports the black box function to facilitate quick fault location and service recovery.
- Fault Diagnostic Management 2.0 (FDM 2.0) accurately locates 93% hardware faults, greatly improving O&M efficiency.

The CH222 V3 provides superior computing performance and a large storage capacity. Featuring Intel® Xeon® E5-2600 v3/v4 series processors (up to 145 W) and support for up to 24 DIMM slots, 15 x 2.5" hard disks, and a 1 GB RAID cache, the CH222 V3 is suitable for big-data analysis and processing applications that require large storage capacity and high computing performance, such as videos, searches, and biological sciences.

Technical Specifications

Form factor	Full-width 2-socket compute node
Number of processors	1 or 2
Processor model	Intel® Xeon® E5-2600 v3/v4 series
Number of DIMMs	24 DDR4 DIMMs, providing a maximum memory capacity of 1.5 TB
Internal Storage	15 x 2.5" SSDs, SAS HDDs, or SATA HDDs Built-in flash memory: 2 x SATA DOM 2 x Micro SD cards (Raid1) 1 x USB 3.0 Disk
RAID support	RAID 0, 1, 10, 5, 50, 6, and 60 512 MB/1 GB RAID cache
PCIe expansion	2 PCIe x16 mezz modules 1 standard PCIe x16 full-height half-length card
Operating systems supported	Microsoft Windows Server 2008/2012 Red Hat Enterprise Linux SUSE Linux Enterprise Server Oracle Linux CentOS Huawei Fusionsphere Citrix XenServer VMware
Operating temperature	5°C to 40°C
Dimensions	Height: 60.46 mm Width: 423 mm Depth: 537.2 mm

HUAWEI CH225 V3 All-Flash Compute Node

Superior performance, ultra-large flash memory

- Supports up to 12 x 2.5" NVMe SSDs and 2 x 2.5" SAS/SATA HDDs or SSDs. Delivers industry-leading NVMe storage capacity per node.
- Supports the full series and all specifications of Intel® Xeon® E5-2600 v3/v4 series processors. Provides 2 x 22-core processors to deliver superior computing capability.
- Provides 24 DDR4 DIMM slots with up to 1.5 TB memory capacity.



Low energy consumption and high efficiency

- Adopts the dynamic energy management technology (DEMT) and power capping technologies for best power consumption control, which remarkably reduces power consumption in low-load operating.
- Delivers high quality thanks to its carrier-class design, mature manufacturing process, and carefully selected components.

Intelligent platform for easy management

- Complies with IPMI V2.0 and supports remote deployment and maintenance functions such as remote maintenance using SOL, KVM over IP, virtual CD-ROM drive, and WebUI to reduce O&M costs.
- Provides efficient and secure power consumption analysis and control capabilities. SSDs can be separately unloaded on the OS.
- Fault Diagnostic Management 2.0 (FDM 2.0) accurately locates 93% hardware faults, greatly improving O&M efficiency.

The CH225 V3 provides superior computing performance and large storage capacity. It uses Intel® Xeon® E5-2600 v3/v4 series processors and supports up to 24 DIMM slots, 12 x 2.5" NVMe SSDs, and 2 x 2.5" hard disks. The CH225 V3 is suitable for scenarios that require high computing performance and large storage capacity, such as high-performance databases, real-time data analysis, and search.

Technical Specifications

Form Factor	Full-width 2-socket compute node
Number of Processors	1 or 2
Processor Model	Intel® Xeon® E5-2600 v3/v4 series
Memory	24 DDR4 DIMMs, providing a maximum memory capacity of 1.5 TB
Internal Storage	12 x 2.5" NVMe SSDs, and 2 x 2.5" SSDs, SAS/SATA HDDs 2 x SATA DOM 2 x MicroSD cards (RAID 1) 1 x USB flash drive (USB 3.0)
RAID	2 x 2.5" SAS/SATA HDDs or SSDs (RAID 0 or 1)
PCIe Expansion	4 x mezzanine cards (x16)
OSs Supported	Microsoft Windows Server 2008/2012 Red Hat Enterprise Linux SUSE Linux Enterprise Server Oracle Linux CentOS Huawei FusionSphere Citrix XenServer VMware
Operating Temperature	5°C - 40°C (41°F - 104°F)
Dimensions	423 mm (width) x 537.2 mm (depth) x 60.46 mm (height)

HUAWEI CH226 V3 Storage Expansion Compute Node

High density and large memory

- Supports the full series of Intel® Xeon® E5-2600 v3/v4 processors to deliver up to 2*22 cores of computing capacity.
- Provides 24 DDR4 DIMMs. Provides a maximum capacity of 1.5TB.
- Supports 6 x 3.5" SAS/SATA HDDs and 2 x 2.5" SAS/SATA HDDs or SSDs, which provide the highest storage capacity on a single node.



Minimum energy for maximum efficiency

- Adopts the dynamic energy saving and power capping technologies to optimally manage and control power consumption with power remarkably reduced in low-load operating.
- Applies superb design, manufacturing processes, and components to ensure high quality.

Intelligent platform for strong management

- Reduces O&M costs by supporting remote deployment and fault location technologies such as SOL, KVM over IP, virtual DVD-ROM drive, WebUI and IPMI 2.0-compliant.
- Provides efficient and secure power consumption analysis and control capabilities.
 - Complies with Intel® NM 3.0.
 - Provides a sub-3s power capping response on each compute node to optimize power consumption control.
 - Supports an intelligent and secure power-off mode for compute nodes.
- Supports the black box function to facilitate quick fault location and service recovery.
- Fault Diagnostic Management 2.0 (FDM 2.0) accurately locates 93% hardware faults, greatly improving O&M efficiency.

The CH226 V3 provides superior computing performance and a large storage capacity. Featuring Intel® Xeon® E5-2600 v3/v4 series processors (up to 145 W) and support for up to 24 DIMM slots, 6 x 3.5" and 2 x 2.5" hard disks, and a 2GB RAID cache, the CH226 V3 is suitable for big-data analysis and processing applications that require large storage capacity and high computing performance, such as Server SAN, biological sciences or VDI.

Technical Specifications

Form Factor	Full-width 2-socket compute node
Number of processors	1 or 2
Processor Model	Intel® Xeon® E5-2600 v3/v4 series
Number of DIMMs	24 DDR4 DIMMs, providing a maximum memory capacity of 1.5TB
Internal Storage	6 x 3.5" SAS/SATA HDDs, and 2 x 2.5" SSDs, SAS/SATA HDDs 2 x SATA DOM 2 x Micro SD cards (Raid1) 1 x USB 3.0 Disk
RAID Supports	RAID 0, 1, 10, 5, 50, 6, 60, 512MB/1GB/2GB RAID cache
PCIe expansion	2 PCIe x16 mezz modules 1 standard PCIe x8 full-height half-length card
OS supported	Microsoft Windows Server 2008/2012 Red Hat Enterprise Linux SUSE Linux Enterprise Server Citrix XenServer VMware
Operating Temperature	5°C to 40°C
Dimensions	Height: 60.46 mm Width: 423 mm Depth: 537.2 mm

HUAWEI CH242 V3 Compute Node

High computing performance, scalability, and reliability

- Supports the full series of Intel® Xeon® E7 v3/v4 processors to deliver up to 4*24 cores of computing capacity.
- 4-socket compute node installed in a full-width slot, supports up to a maximum of 32 DDR4 DIMMs.
- Supports a maximum of eight 2.5-inch SAS HDDs, SATA HDDs, or SSDs, four of them are compatible with NVMe SSDs, and provides a maximum of 2 PCIe slots for standard PCIe cards.
- Uses a real-time, accurate error-checking and fault tolerance mechanism, and supports WHEA and eMCA Gen1.



High efficiency and energy-saving

- Complies with Intel® NM 2.0 dynamic power capping specifications.
- Completes power capping operations within 3 seconds.
- Supports an intelligent, secure power-on mode.

Easy management with the intelligent platform

- Reduces O&M costs by using remote deployment and fault locating methods including SOL, KVM over IP, virtual CD-ROM drive, and WebUIs in compliance with IPMI 2.0.
- Supports the black box function to facilitate fault location, quickly recovering services.
- Fault Diagnostic Management 2.0 (FDM 2.0) accurately locates 93% hardware faults, greatly improving O&M efficiency.

The CH242 V3, based on the E7 v3/E7 v4 processor, provides high processing performance, scalability, and reliability to address computing-intensive applications and supports efficient, flexible mission-critical enterprise services. Use the CH242 V3 for large data sets and transaction-intensive databases, ERP, BI platform. It can also apply to cloud computing and virtualization.

Technical Specifications

Form Factor	Full-width 4-socket compute node
Number of processors	2 or 4
Processor Model	Intel® Xeon® E7 v3/v4
Number of DIMMs	32 DDR4 DIMMs, the max capacity is 2TB
Internal Storage	Eight 2.5" SAS/SATA HDDs, or SSDs, four of them are compatible with NVMe SSDs 2 x Micro SD cards 1 x USB2.0 Disk
RAID Supports	RAID0/1/10/5/50/6/60, 1GB RAID Cache
PCIe expansion	4 PCIe x16 MEZZ modules supports two FHHL PCIe cards, when the two built-in PCIe slots are used, some DIMM slots cannot be used
OS supported	Microsoft Windows Server 2008/2012 Red Hat Enterprise Linux SUSE Linux Enterprise Server Oracle Linux Oracle Solaris CentOS Huawei Fusionsphere Citrix XenServer VMware
Operating Temperature	5°C to 40°C
Dimensions	423mm(width) x 537.2mm(depth) x 60.46mm(height)

HUAWEI E9000 Switch Module

The E9000 supports several types of switch modules: CX110 GE switch module, CX111 GE switch module, CX116 GE pass through module, CX210 8G FC switch module, CX220 16G FC switch module, CX310 10GE switch module, CX311 10GE/FCoE converged switch module, CX317 10GE pass through module, CX318 10GE pass through module, CX320 converged switch module, CX611 InfiniBand switch module, CX620 InfiniBand EDR switch module, CX710 40GE switch module, and CX912 10GE/FC multi-plane switch module, CX915 GE/FC multi-plane switch module. You can select the one that best suits your service requirements for network I/O. Their detailed specifications are described in the tables below:

CX110 GE switch module



Network ports	12 x GE +4 x 10GE SFP+ uplink 32 x GE downlink 2 x 40GE Interconnect(can be used as a stack)
Network features	L2: VLAN/MSTP/LACP/TRILL/Stack/IGMP L3: RIP/OSPF/ISIS/BGP/RRP/BFD/PIM QoS: ACL/CAR/ DiffServ Security: IPSG/MFF/DAI /DHCP Snooping
Management port	2 x RS232 management serial ports (one each for services and management)
Dimensions	35.06mm(width) x 272.15mm(depth) x 388.55mm(height)

CX111 GE switch module



Network ports	4 x 10GE SFP+ and 12 x GE uplink 32 x GE downlink
Network features	L2: VLAN/MSTP/LACP/Stack/IGMP/Smart Link/Monitor Link L3: RIP/OSPF/ISIS/BGP/RRP/BFD/PIM/IPV6 QoS: ACL/CAR/DiffServ Security: IPSG/MFF/FSB/DAI/DHCP Snooping/sFlow/Netstream
Management port	2 x RS232 management serial ports (one each for services and management)
Dimensions	35.06mm(width) x 272.15mm(depth) x 388.55mm(height)

CX116 GE pass through module



Network port	32 x GE uplink 32 x GE downlink
Dimensions	35.06mm(width) x 272.15mm(depth) x 388.55mm(height)

CX210 8G FC switch module



Network ports	8 x 8G FC uplink ports(SFP+), 4 ports activate in default, other 4 ports activate by license 16 x 8G FC downlink
Network features	Supports the FC mode and AG mode (NPV) Supports the F_Port, E_Port (license required), and N_Port Supports NPIVs, up to 255 NPIVs per port Supports the aggregation of up to eight 8GE ports by using a license Supports advanced zoning (default zoning, port/WWN zoning, and broadcast zoning)
Management port	2 x RS232 management serial ports (one each for services and management)
Dimensions	35.06mm(width) x 272.15mm(depth) x 388.55mm(height)

CX220 16G FC switch module



Network Interface	8*16G FC uplink ports (SFP+), 4 ports activate in default, other 4 ports activate by license 16*16G FC downlink ports
Network features	Supports the FC mode and AG mode (NPV) Supports the F_Port, E_Port (license required), and N_Port Supports NPIVs, up to 255 NPIVs per port Supports the aggregation of up to eight 16GE ports by using a license Supports advanced zoning (default zoning, port/WWN zoning, and broadcast zoning)
Management port	2 console (RS232) port, one for device management, the other for FC switch module Support SOL/console, SSH, Web (https), SNMPv1/v3
Dimensions	35.06mm(width) x 272.15mm(depth) x 388.55mm(height)

CX310 10GE converged switch module



Network port	16 x 10GE uplink 32 x 10GE downlink
Network features	L2: VLAN/MSTP/LACP/TRILL/Stack/IGMP/Smart Link/Monitor Link L3: RIP/OSPF/ISIS/BGP/RRP/BFD/PIM/IPV6 QoS: DCBX/PFC/ETS/ACL/CAR/DiffServ Security: IPSG/MFF/FSB/DAI/DHCP Snooping/sFlow/Netstream
Management port	2 x RS232 management serial ports (one each for services and management)
Dimensions	35.06mm(width) x 272.15mm(depth) x 388.55mm(height)

CX311 10GE/FCoE converged switch module



Network port	16 x 10GE SFP+ and 8 x 8G FC SFP+ uplink; 32 x 10GE downlink
Network features	L2: VLAN/MSTP/LACP/TRILL/Stack/IGMP/Smart Link/Monitor Link L3: RIP/OSPF/ISIS/BGP/RRP/BFD/PIM/IPV6 QoS: DCBX/PFC/ETS/ACL/CAR/DiffServ Security: IPSG/MFF/FSB/DAI/DHCP Snooping/sFlow/Netstream FC: supports the FC mode (full fabric) and TR mode (NPV) Supports the F_Port, E_Port (license required), and N_Port Supports NPIVs, up to 255 NPIVs per port Supports hard zoning and soft zoning
Management port	2 x RS232 management serial ports (one each for services and management)
Dimensions	35.06mm(width) x 272.15mm(depth) x 388.55mm(height)

CX317 10GE pass through module



Network port	Uplink: 32 x 10GE SFP+ ports Downlink: 32 x 10GE ports
Dimensions	35.06mm(width) x 272.15mm(depth) x 388.55mm(height)

CX318 10GE pass through module



Network port	Uplink: 32 x 10GE SFP+ ports Downlink: 32 x 10GE ports
Dimensions	35.06mm(width) x 272.15mm(depth) x 388.55mm(height)

CX320 10GE/40GE/FCoE/FC converged switch module



Network port	8 x 10GE + 2 x 40GE uplink, with 8 x 10GE/8G FC flexible interface card optional 32 x 10GE downlink
Network features	L2/L3/SmartLink/Monitor Link/BFD/VRRP/SmartChannel Supports FSB/FCF/NPV Openflow1.3/XLAN
Dimensions	35.06mm(width) x 272.15mm(depth) x 388.55mm(height)

CX611 Infiniband QDR/ FDR switch module



Network port	18 QDR/FDR InfiniBand QSFP+ uplink 16 QDR/FDR InfiniBand downlink
Network features	multicast forwarding and replication/load balancing/re-route around failed link/VL/SL/SL to VL mapping/SM/SMA/Low latency forwarding/credit based flow control
Management port	In-band management
Dimensions	35.06mm(width) x 272.15mm(depth) x 388.55mm(height)

CX620 Infiniband EDR switch module



Network port	18 EDR InfiniBand uplink 16 EDR InfiniBand downlink
Network features	Compliant with IBTA 1.21 and 1.3 9 virtual lanes: 8 data + 1 management 256 to 4Kbyte MTU Adaptive Routing
Dimensions	35.06mm(width) x 272.15mm(depth) x 388.55mm(height)

CX710 40GE switch module



Network port	8 x 40GE QSFP+ uplink, among which 6*40GE uplink ports can be converted into four 10GE ports respectively 16 x 40GE downlink, each port can be converted into two 10GE ports
Network features	L2: VLAN/MSTP/LACP/TRILL/Stack/IGMP/Smart Link/Monitor Link L3: RIP/OSPF/ISIS/BGP/RRP/BFD/PIM/IPV6 QoS: DCBX/PFC/ETS/ACL/CAR/DiffServ Security: IPSG/MFF/FSB/DAI/DHCP Snooping/sFlow/Netstream
Management port	2 x RS232 management serial ports (one each for services and management)
Dimensions	35.06mm(width) x 272.15mm(depth) x 388.55mm(height)

CX912 10GE/FC multi-plane switch module



Network port	16 x 10GE SFP+ and 8 x 8G FC SFP+ uplink, 4 FC ports activate in default, other 4 FC ports activate by license 32 x 10GE/16 x 8G FC downlink
Network features	L2: VLAN/MSTP/LACP/TRILL/Stack/IGMP/Smart Link/Monitor Link L3: RIP/OSPF/ISIS/BGP/RRP/BFD/PIM/IPV6 QoS: DCBX/PFC/ETS/ACL/CAR/DiffServ Security: IPSG/MFF/FSB/DAI/DHCP Snooping/sFlow/Netstream Supports the FC mode and AG mode (NPV) Supports the F_Port, E_Port (license required), and N_Port Supports NPivs, up to 255 NPivs per port Supports the aggregation of up to eight 8G ports by using a license Supports advanced zoning (default zoning, port/WWN zoning, and broadcast zoning)
Management port	2 x RS232 management serial ports (one each for services and management)
Dimensions	35.06mm(width) x 272.15mm(depth) x 388.55mm(height)

CX915 GE/FC multi-plane module



Network port	4 x 10GE SFP+ and 12 x GE and 8 x 8G FC SFP+ uplink 32 x GE and 16 x 8G FC downlink
Network features	L2: VLAN/MSTP/LACP/Stack/IGMP/Smart Link/Monitor Link L3: RIP/OSPF/ISIS/BGP/RRP/BFD/PIM/IPV6 QoS: ACL/CAR/DiffServ Security: IPSG/MFF/FSB/DAI/DHCP Snooping/sFlow/Netstream integrates a Qlogic FC switch
Management port	2 x RS232 management serial ports (one each for services and management)
Dimensions	35.06mm(width) x 272.15mm(depth) x 388.55mm(height)





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